

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance – Junction-to-Lead (Note 1)	$R_{\theta JL}$	24	$^{\circ}\text{C/W}$
Thermal Resistance – Junction-to-Ambient (Note 2)	$R_{\theta JA}$	80	$^{\circ}\text{C/W}$

1. Mounted with minimum recommended pad size, PC Board FR4.
2. 1 inch square pad size (1 x 0.5 inch for each lead) on FR4 board.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value		Unit
		$T_J = 25^{\circ}\text{C}$	$T_J = 125^{\circ}\text{C}$	
Maximum Instantaneous Forward Voltage (Note 3) ($i_F = 1.0\text{ A}$) ($i_F = 2.0\text{ A}$)	V_F	0.51 0.63	0.475 0.55	V
Maximum Instantaneous Reverse Current (Note 3) ($V_R = 60\text{ V}$)	I_R	0.2	20	mA

3. Pulse Test: Pulse Width $\leq 250\text{ }\mu\text{s}$, Duty Cycle $\leq 2.0\%$.

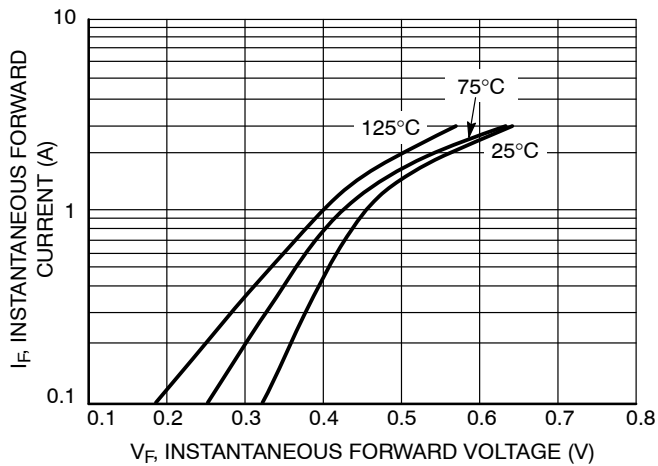


Figure 1. Typical Forward Voltage

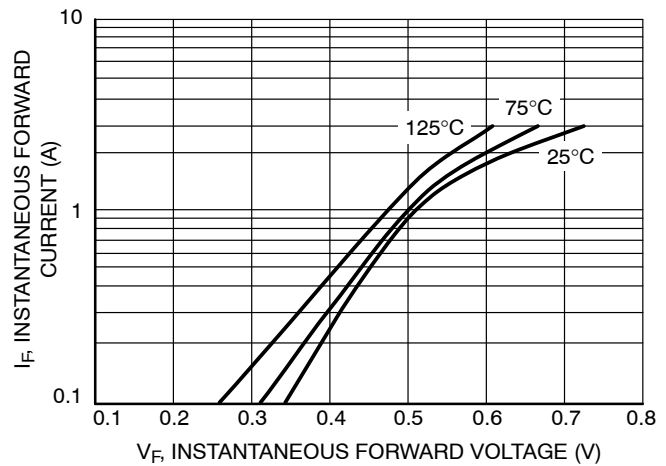


Figure 2. Maximum Forward Voltage

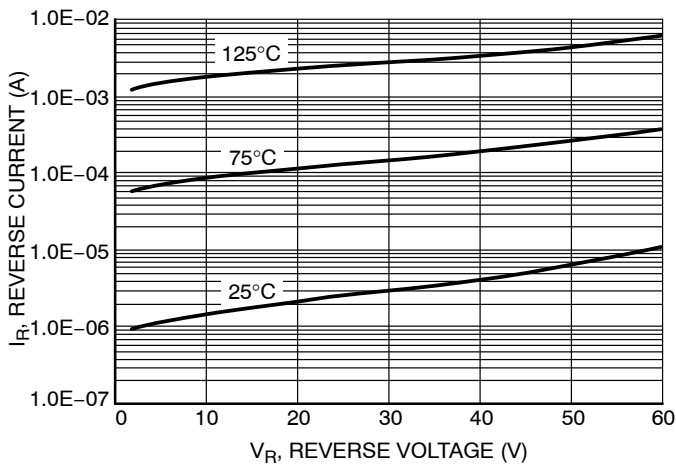


Figure 3. Typical Reverse Current

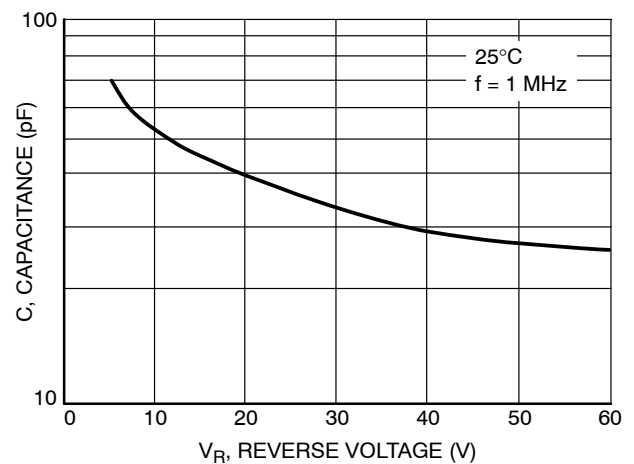


Figure 4. Typical Capacitance

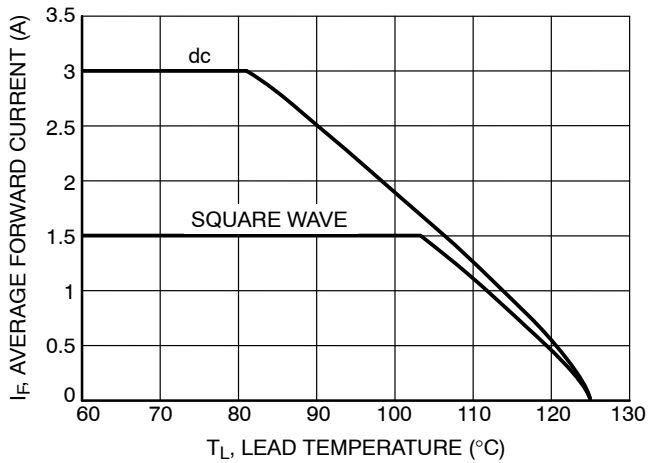


Figure 5. Current Derating – Junction to Lead

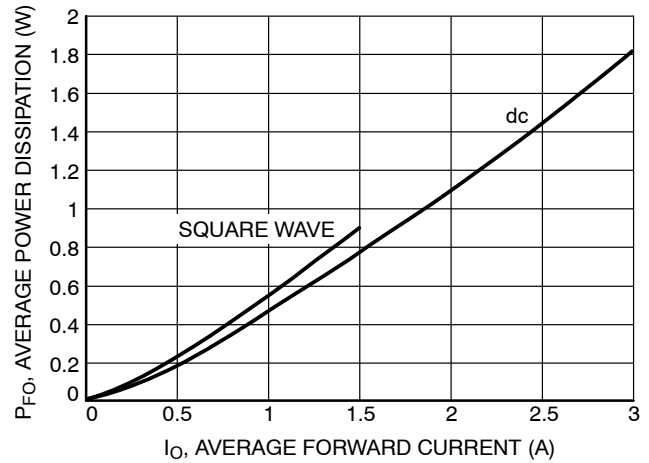


Figure 6. Forward Power Dissipation

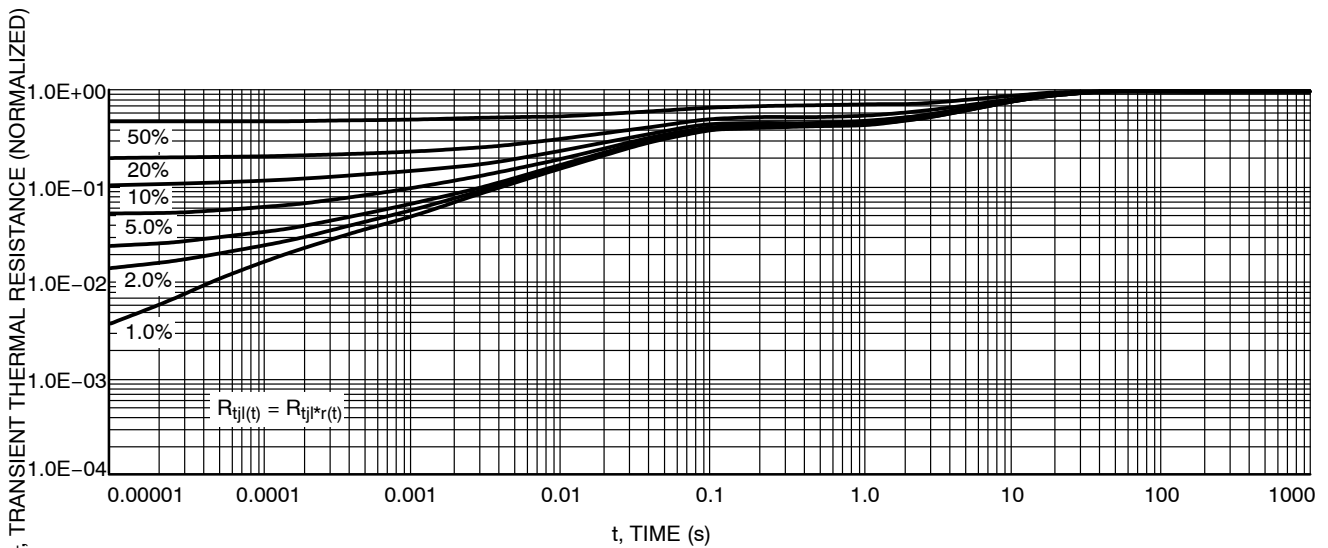


Figure 7. Thermal Response – Junction to Case

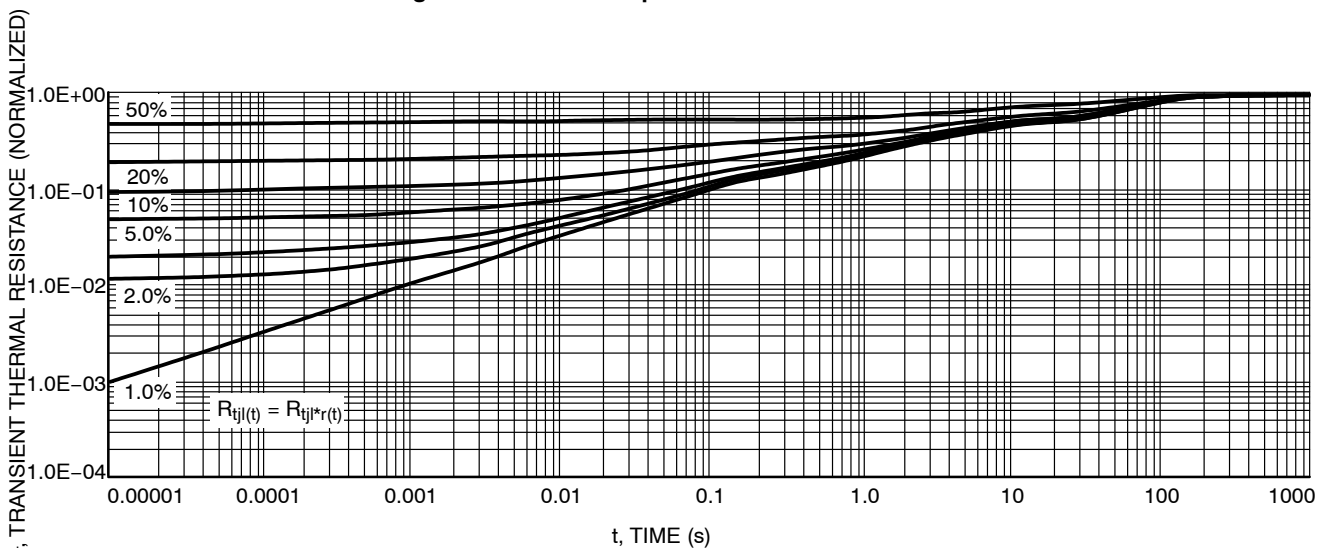
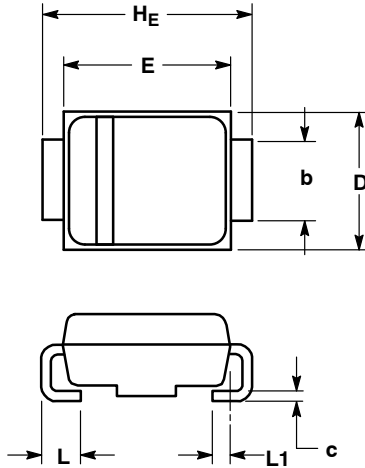


Figure 8. Thermal Response – Junction to Ambient

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PACKAGE DIMENSIONS

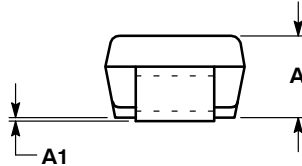
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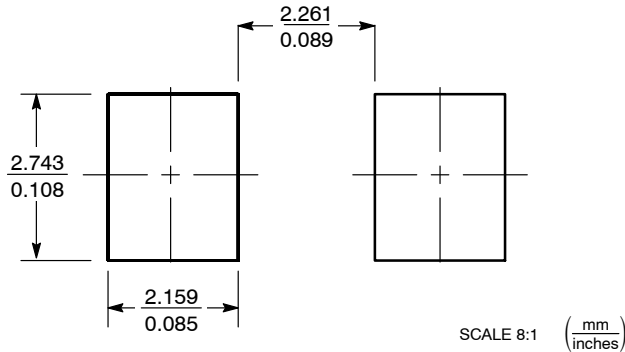
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.


DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.90	2.13	2.45	0.075	0.084	0.096
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.96	2.03	2.20	0.077	0.080	0.087
c	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
E	4.06	4.32	4.60	0.160	0.170	0.181
HE	5.21	5.44	5.60	0.205	0.214	0.220
L	0.76	1.02	1.60	0.030	0.040	0.063
L1	0.51 REF			0.020 REF		



SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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